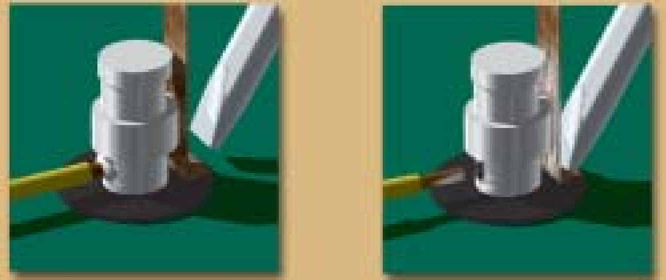
Desoldering Applications

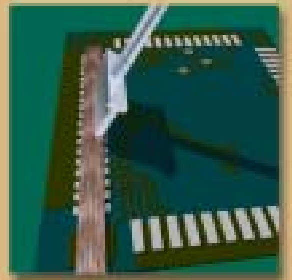


Wire Wrap Pins
Desolder pins for easy removal. Removes solder buildup. Eliminates potential intermittent problems.

Lugs/Posts
Wicks solder completely, eliminating solder splash or drip. Leaves terminal fluxed and ready for resoldering.

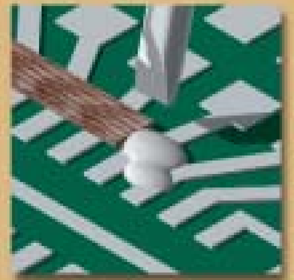
Components
Easily removes solder from components with straight or clinched leads. Minimum heat required. No damage to board or components.

Cleaning Applications



SMT Pads
Quickly and safely desolders entire rows of SMT pads. Applications-specific sizes desolder individual fine-pitch SMT pads.

BGA Pads
Safely removes solder from BGA pads and chips in three to four passes. Completely removes all residual solder and facilitates chip repositioning.



Solder Bridges
Completely removes solder bridges. Eliminates potential shorts. No damage to boards or circuitry.

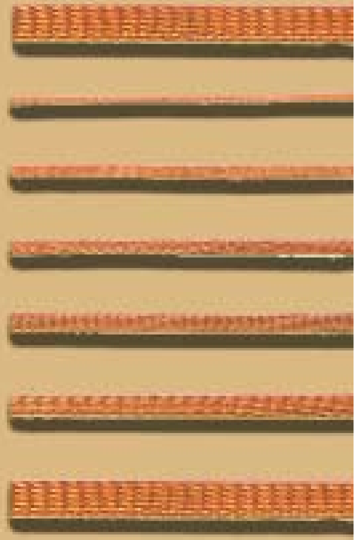
Clean Script
Selectively retouches etched script. Improves aesthetic appearance. Eliminates secondary identification. Easy to use.

Blobs
Eliminates and removes blobs as well as shorts and icicles. Leaves circuitry smooth. Cleans potential problem areas.

Finger Connectors
Cleans finger connectors and surface mount pads.

Braid Sizes

BGA	Purple
.030"/0.8mm	White
.060"/1.5mm	Yellow
.080"/2.0mm	Green
.110"/2.8mm	Blue
.145"/3.7mm	Brown
.210"/5.3mm	Red



Chem-Wik® Desoldering Braid

Chem-Wik® Desoldering Braid
As the standard desoldering braid for service and repair, Chem-Wik® Desoldering Braid ensures fast and safe desoldering. The ultra-pure, oxygen free copper braid quickly and completely removes solder from circuit boards and components. Its fast wicking action protects components from harmful heat damage. PermaPak™ Barrier Packaging ensures ultimate braid freshness and seals out harmful effects of the environment and protecting against oxidation.

Chem-Wik® Desoldering Braid:
Meets or exceeds the greatest range of perfomance standards:
- MIL-F-14256F Type R
- NASA STD-8739.3 Soldered Electrical Connections
- ANSI/IPC J STD-004, Type ROL0

Static Dissipative Packaging:
- DOD Standard 1686C and MIL-HDBK-263B
- Mil-Std-2000A
- Mil-B-81705C Static Decay Rate Provision

Chem-Wik® Rosin
The fast, safe rosin flux desoldering braid for removing solder from leads and components

- Coated with ultra high purity rosin
- Quickly and thoroughly removes solder
- Noncorrosive Type R rosin flux

Chem-Wik® Rosin SD
The fast, safe rosin flux desoldering braid packaged in static dissipative bobbins

- Reduces the risk of damage associated with static electricity
- Coated with noncorrosive ultra high purity Type R rosin flux
- Quickly and thoroughly removes solder

PermaPak™ Barrier Packaging contains 25 bobbins per package

Chem-Wik® Product Selection Guide

PRODUCT	COLOR	SIZE	5' 1.5m	25' 7.5m	50' 15.0m	100' 30.5m	500' 152.5m	APPLICATION
Chem-Wik® Rosin	Gray	.030"/0.8mm		2-25L	2-50L	2-100L	2-500L	Micro-Circuits
	Yellow	.050"/1.3mm		5-25L	5-50L	5-100L	5-500L	Small Pads
	Green	.075"/1.9mm		7-25L	7-50L	7-100L	7-500L	Medium Pads
	Blue	.100"/2.5mm		10-25L	10-50L	10-100L	10-500L	Large Pads
Chem-Wik® Rosin SD	Gray	.030"/0.8mm	2-5L					Micro-Circuits
	Yellow	.050"/1.3mm	5-5L					Small Pads
	Green	.075"/1.9mm	7-5L					Medium Pads
	Blue	.100"/2.5mm	10-5L					Large Pads

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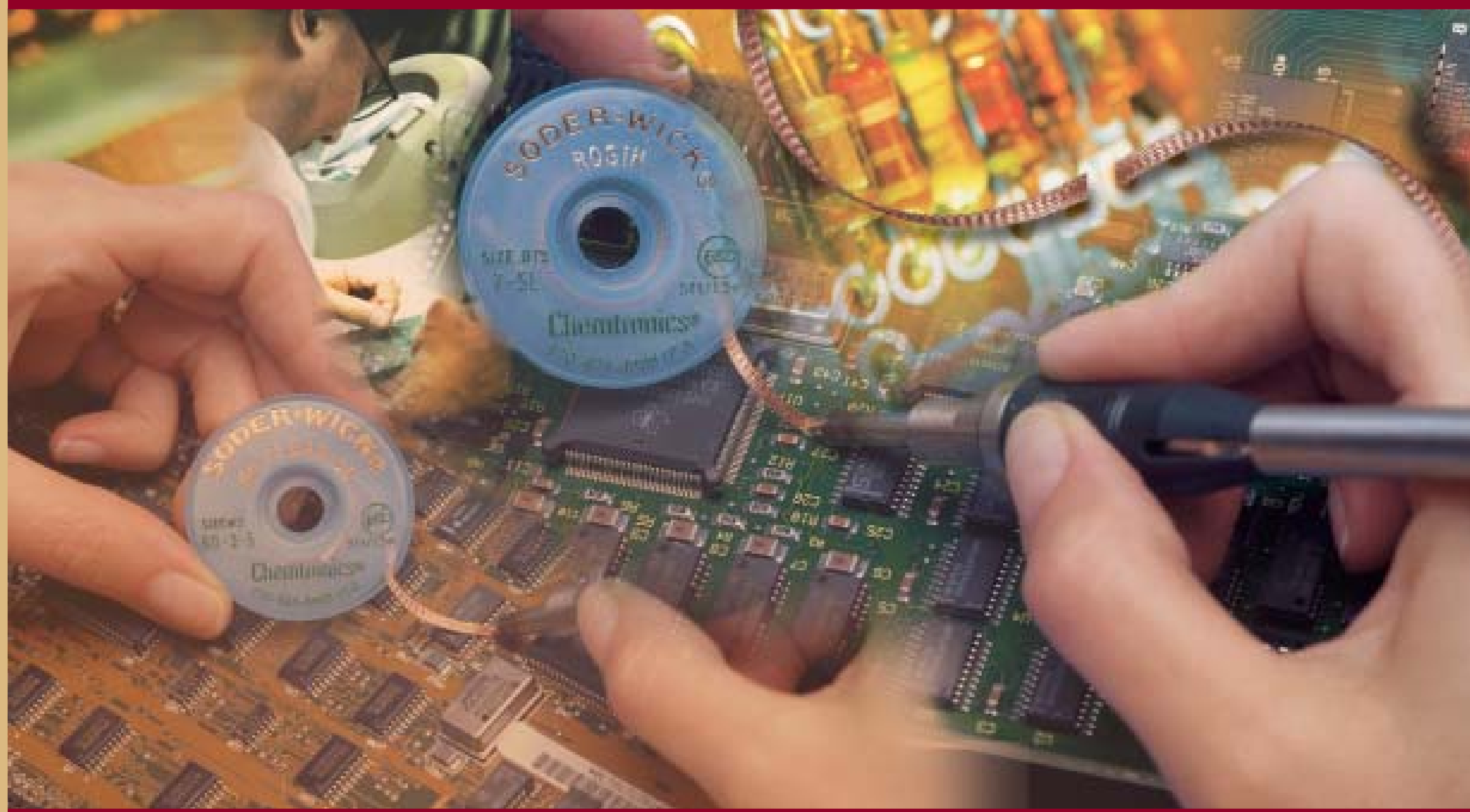

The Leader in Desoldering Technology

Soder-Wick® — World's Leading Brand of Desoldering Braid

Soder-Wick®, the world's leading brand of desoldering braid, is the fastest, cleanest and safest braid in the industry.

It significantly reduces rework/repair time and minimizes the risk of heat damage to the board. Its geometrically precise weave design allows for maximum capillary action and solder capacity. Soder-Wick® Desoldering Braid optimizes heat transfer through the braid and into the solder joint, resulting in faster wicking action than any other competitive brand. Minimal flux residue on the board speeds up the cleaning process, or eliminates it entirely.

Soder-Wick® Desoldering Braid is available in the most comprehensive variety of widths, lengths and flux types.

Application-specific sizes allow for precision solder removal in a flash. Sealed in Performance Pak™ Barrier Packaging and VacuPak™ Vacuum Sealed Packaging, Soder-Wick® Desoldering Braid is completely protected from the harmful effects of the environment. The VacuPak™ vacuum-sealed can guarantees the braid to be as fast and fresh as the day it was made. The can serves as a protective storage container once the pack has been opened and is also easily stacked on the shelf. Its superior packaging provides predictable quality and performance, time and time again.

Soder-Wick® Desoldering Braid meets or exceeds the greatest range of qualitative and performance standards:

- MIL-F-14256 F type R flux
- NASA-STD-8739.3 Soldered Electrical Connections
- DOD-STD-883E, Method 2022
- ANSI/IPC J STD-004, Type ROL0

Static Dissipative Packaging:

- Qualifies under MIL-STD-1686C and MIL-HDBK-263B as a non-ESD generator
- Meets the Static Decay Rate Provision of MIL-B-81705C and MIL-STD-2000A

Soder-Wick® No Clean SD:

- Meets MIL-STD-883B, Bellcore TR-NWT-000078, ANSI/IPC J SF-818
- Meets parameters tested by the Singapore Institute of Standards and Industrial Research (SISIR) for Solderability
- ANSI/IPC J STD-004, Type ROL0

All 5' and 10' bobbins are offered on static dissipative bobbins, and only Soder-Wick® static dissipative bobbins are labeled by heat stamping. This eliminates paper labels that increase the risk of ESD damage. Competitive desoldering braid does not offer this increased level of protection.

Fastest, Cleanest and Safest Braid in the Industry
www.chemtronics.com

Soder-Wick® Lead-Free SD

The fastest, safest desoldering braid formulated specifically for use with lead-free applications

- Engineered specifically for high temperature, lead-free solders
- Transfers heat to the solder joint more quickly and efficiently than conventional desoldering braids
- Specifically designed for all lead-free solders
- Can also be used with Tin/Lead solders
- Packaged in ESD-safe static dissipative bobbins
- Minimizes the risk of damage associated with static electricity
- Noncorrosive ultra high purity no-clean flux
- Will not leave ionic contamination on the boards
- Especially effective at removing residual solder from SMT pads
- RoHS compliant

Soder-Wick® BGA

The most effective, economical way to safely and completely remove solder from BGA pads and chips

- Sized and designed specifically for BGA pad and chip rework/repair
- Entire BGA pads cleaned in three to four passes
- Available in rosin and no-clean fluxes
- Packaged in ESD-safe static dissipative bobbins

Soder-Wick® Rosin

The fastest, safest rosin flux desoldering braid for removing solder from printed circuit boards

- Noncorrosive ultra high purity Type R rosin flux
- Minimizes the risk of heat damage to the board
- Will not leave ionic contamination on the boards

Soder-Wick® Rosin SD

The fastest, safest rosin flux desoldering braid packaged in static dissipative bobbins

- Soder-Wick® Rosin packaged in ESD-safe static dissipative bobbins
- Minimizes the risk of damage associated with static electricity
- Noncorrosive ultra high purity Type R rosin flux
- Minimizes the risk of heat damage to the board
- Will not leave ionic contamination on the boards

Soder-Wick® No Clean SD

The fastest, cleanest no-clean flux desoldering braid packaged in static dissipative bobbins

- Soder-Wick® No Clean packaged in ESD-safe static dissipative bobbins
- Minimizes the risk of damage associated with static electricity
- Patented noncorrosive, halide free, organic no-clean flux
- Desolders up to 40% faster than competitive no-clean braids and leaves boards cleaner
- Meets Bellcore TR-NWT-000078 and ANSI IPC SF-818 for Surface Insulation Resistance

Soder-Wick® Unfluxed

The unfluxed desoldering braid which can be coated with any flux type

- Can be coated with any flux type
- Allows for a constant flux type throughout the production process
- Provides quick and safe desoldering

Soder-Wick® Unfluxed SD

The unfluxed desoldering braid packaged in static dissipative bobbins

- Soder-Wick® Unfluxed packaged in ESD-safe static dissipative bobbins
- Minimizes the risk of damage associated with static electricity
- Can be coated with any flux type
- Allows for a constant flux type throughout the production process
- Provides quick and safe desoldering

Soder-Wick® Product Selection Guide

PRODUCT	SIZE		COLOR	5' 1.5m	10' 3.0m	25' 7.5m	100' 30.5m	500' 152.5m	VACUPAK™	APPLICATION
Soder-Wick® Lead-Free SD	2	.060"/1.5mm	Yellow	40-2-5	40-2-10				SW14025	Small Pads, SMDs
	3	.080"/2.0mm	Green	40-3-5	40-3-10				SW14035	Medium Pads
	4	.110"/2.8mm	Blue	40-4-5	40-4-10				SW14045	Large Pads
Soder-Wick® BGA Rosin	BGA		Purple	80-BGA-5					SW180BGA	BGA Pads and Chips
Soder-Wick® BGA No Clean	BGA		Purple	60-BGA-5					SW160BGA	BGA Pads and Chips
Soder-Wick® Rosin	1	.030"/0.8mm	White			50-1-25				SMD, Micro-Circuits
	2	.060"/1.5mm	Yellow			50-2-25	50-2-100	50-2-500		Small Pads, SMDs
	3	.080"/2.0mm	Green			50-3-25	50-3-100	50-3-500		Medium Pads
	4	.110"/2.8mm	Blue			50-4-25	50-4-100	50-4-500		Large Pads
	5	.145"/3.7mm	Brown			50-5-25				Terminals
	6	.210"/5.3mm	Red			50-6-25				Large Lugs
Soder-Wick® Rosin SD	1	.030"/0.8mm	White	80-1-5	80-1-10				SW18015	SMD, Micro-Circuits
	2	.060"/1.5mm	Yellow	80-2-5	80-2-10				SW18025	Small Pads, SMDs
	3	.080"/2.0mm	Green	80-3-5	80-3-10				SW18035	Medium Pads
	4	.110"/2.8mm	Blue	80-4-5	80-4-10				SW18045	Large Pads
	5	.145"/3.7mm	Brown	80-5-5	80-5-10				SW18055	Terminals
	6	.210"/5.3mm	Red	80-6-5						Large Lugs
Soder-Wick® No Clean SD	1	.030"/0.8mm	White	60-1-5	60-1-10				SW16015	SMD, Micro-Circuits
	2	.060"/1.5mm	Yellow	60-2-5	60-2-10				SW16025	Small Pads, SMDs
	3	.080"/2.0mm	Green	60-3-5	60-3-10				SW16035	Medium Pads
	4	.110"/2.8mm	Blue	60-4-5	60-4-10				SW16045	Large Pads
	5	.145"/3.7mm	Brown	60-5-5	60-5-10				SW16055	Terminals
	6	.210"/5.3mm	Red	60-6-5						Large Lugs
Soder-Wick® Unfluxed	2	.060"/1.5mm	Yellow			70-2-25				Small Pads, SMDs
	3	.080"/2.0mm	Green			70-3-25				Medium Pads
Soder-Wick® Unfluxed SD	2	.060"/1.5mm	Yellow		75-2-10					Small Pads, SMDs
	3	.080"/2.0mm	Green		75-3-10					Medium Pads
	4	.110"/2.8mm	Blue		75-4-10					Large Pads

All 5' and 10' Soder-Wick® Desoldering Braid is offered on static dissipative bobbins. Performance Pak™ Barrier Packaging contains 25 bobbins per package.

VacuPak™ Vacuum Sealed Packaging

Guarantees Soder-Wick® Desoldering Braid to be as fast and fresh as the day it was made. The VacuPak™ can contains 10 bobbins with 5 feet of braid on each bobbin.

Данный компонент на территории Российской Федерации

Вы можете приобрести в компании MosChip.

Для оперативного оформления запроса Вам необходимо перейти по данной ссылке:

http://moschip.ru/get-element

Вы можете разместить у нас заказ для любого Вашего проекта, будь то серийное производство или разработка единичного прибора.

В нашем ассортименте представлены ведущие мировые производители активных и пассивных электронных компонентов.

Нашей специализацией является поставка электронной компонентной базы двойного назначения, продукции таких производителей как XILINX, Intel (ex.ALTERA), Vicor, Microchip, Texas Instruments, Analog Devices, Mini-Circuits, Amphenol, Glenair.

Сотрудничество с глобальными дистрибьюторами электронных компонентов, предоставляет возможность заказывать и получать с международных складов практически любой перечень компонентов в оптимальные для Вас сроки.

На всех этапах разработки и производства наши партнеры могут получить квалифицированную поддержку опытных инженеров.

Система менеджмента качества компании отвечает требованиям в соответствии с ГОСТ Р ИСО 9001, ГОСТ РВ 0015-002 и ЭС РД 009

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